

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT6149672

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
MASAKI ODAWARA	06/04/2020
RECEIVING PARTY DATA	
Name:	STANLEY ELECTRIC CO., LTD.
Street Address:	2-9-13, NAKAMEGURO
Internal Address:	MEGURO-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	153-8636
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16899100
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	ST3001-0626
NAME OF SUBMITTER:	DAVID J. KENEALY
SIGNATURE:	/david j. kenealy/
DATE SIGNED:	06/11/2020
Total Attachments: 1	
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Combined Declaration and Assignment

Title of Invention	SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREFOR	
<p>As the below named inventor, I hereby declare that:</p> <p>This declaration is directed to: <input checked="" type="checkbox"/> The attached application, or</p> <p style="margin-left: 150px;"><input type="checkbox"/> United States application or PCT international application</p> <p style="margin-left: 150px;">number _____ filed on _____</p> <p>The above-identified application was made or authorized to be made by me.</p> <p>I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.</p> <p>In consideration of value received, I sell and assign to <u>STANLEY ELECTRIC CO., LTD.</u>, having a business address at <u>2-9-13, Nakameguro, Meguro-ku, Tokyo, 153-8636, JAPAN</u>, its successors, assigns or nominees, hereinafter referred to as "Assignee", my entire right, title and interest in and to said invention, and in and to all applications for patent and patents for said invention, in all countries of the world, including all divisions, reissues, continuations, substitutions and extensions thereof and all rights arising under or pursuant to any and all international agreements, treaties or laws relating to the protection of intellectual property, including rights of priority, resulting from the filing of any of said applications.</p> <p>I authorize said Assignee to file and prosecute an application or applications for patent for said invention as the applicant, and I request any official whose duty it is to issue patents, to issue any patent on said invention to said Assignee.</p> <p>I agree that on request and without further consideration, but at the expense of said Assignee, I will communicate to said Assignee or its representatives all facts known to me respecting said invention and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue, or other applications, make all rightful oaths and declarations, and generally do everything possible to aid said Assignee to obtain and enforce proper patent protection for said invention in all countries.</p> <p>I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.</p>		
LEGAL NAME OF INVENTOR		
Masaki ODAWARA	<i>Masaki Odawara</i>	4-Jun-20
Inventor (printed name)	Signature	Date